

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Appl. for Reissue No. : 09/714,680  
Patent No. : 6,054,198  
Applicant : Bunyan *et al.*  
Filed : November 16, 2000  
Title : Conformal Thermal Interface  
Material For Electronic Components

TC/A.U. : 1773  
Examiner : S. Ahmed

Docket No. : 2802-257-006

Honorable Commissioner For Patents  
Alexandria, VA 22313-1450

DO NOT ENTER: /SA/  
04/15/2008

**AMENDMENT**

In response to the Office action of November 27, 2007, leave to amend the above-identified application as follows is respectfully requested:

**Amendments to the Claims** are reflected in the listing of the claims which begins on page 2 of this paper.

**Remarks** begin on page 4 of this paper.